

SN54LS595, SN54LS596, SN74LS595, SN74LS596 8-BIT SHIFT REGISTERS WITH OUTPUT LATCHES

SDLS006

D2634, JANUARY 1981 (REVISED MARCH 1988)

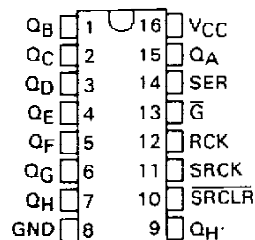
- 8-Bit Serial-In, Parallel-Out Shift Registers with Storage
- Choice of 3-State ('LS595) or Open-Collector ('LS596) Parallel Outputs
- Shift Register Has Direct Clear
- Accurate Shift Frequency: DC to 20 MHz

description

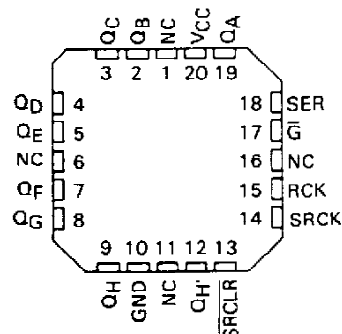
These devices each contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state ('LS595) or open-collector ('LS596) outputs. Separate clocks are provided for both the shift register and the storage register. The shift register has a direct-overriding clear, serial input, and serial output pins for cascading.

Both the shift register and storage register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the shift register state will always be one clock pulse ahead of the storage register.

SN54LS595, SN54LS596 . . . J OR W PACKAGE
SN74LS595, SN74LS596 . . . N PACKAGE
(TOP VIEW)

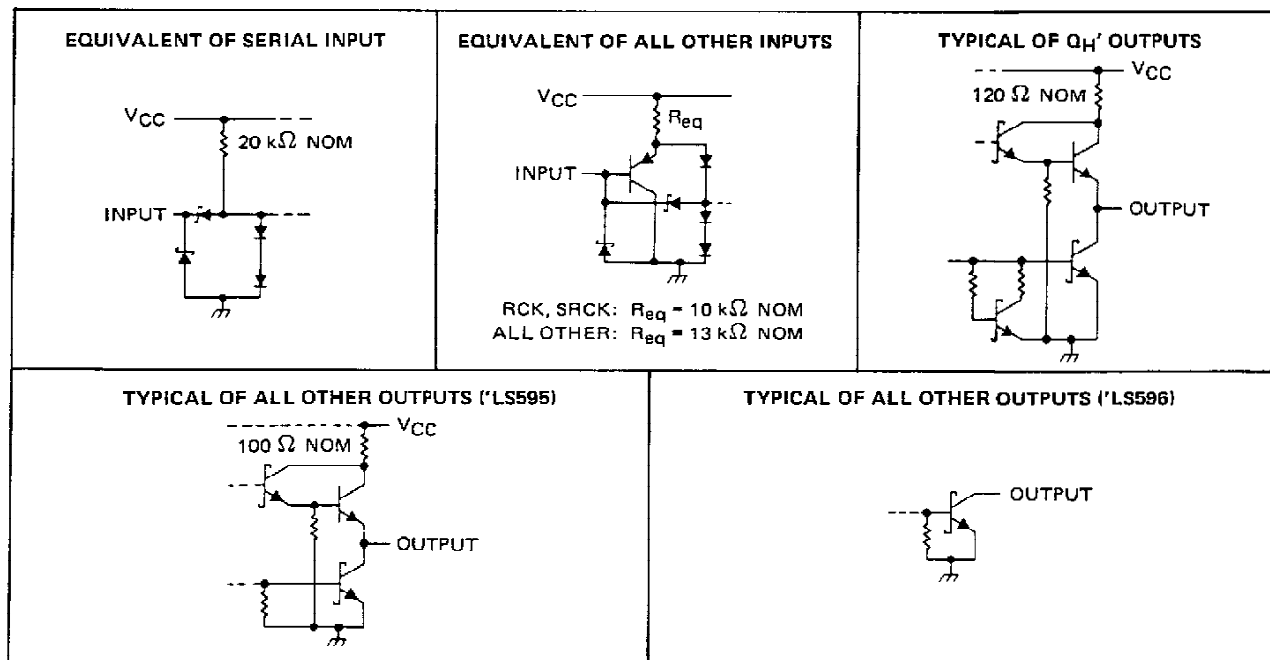


SN54LS595, SN54LS596 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

schematics of inputs and outputs



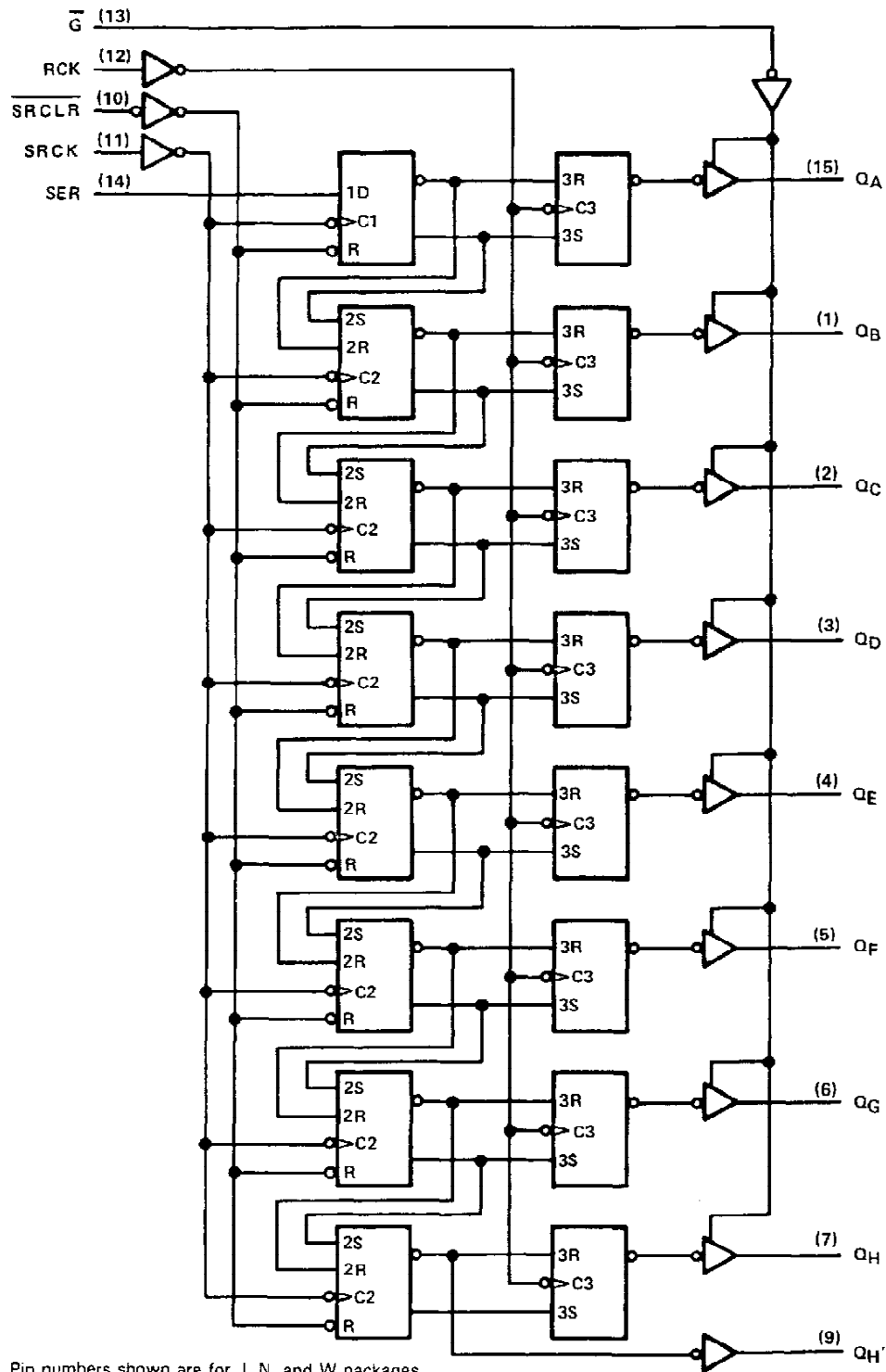
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TEXAS
INSTRUMENTS

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SN54LS595, SN54LS596, SN74LS595, SN74LS596 **8-BIT SHIFT REGISTERS WITH OUTPUT LATCHES**

logic diagram (positive logic)



Pin numbers shown are for J, N, and W packages.

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SN54LS595, SN54LS596, SN74LS595, SN74LS596
8-BIT SHIFT REGISTERS WITH OUTPUT LATCHES

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS †	SN54LS*		SN74LS*		UNIT		
			MIN	TYP‡	MAX	MIN		TYP‡	MAX
V _{IK}		V _{CC} = MIN, I _I = - 18 mA			- 1.5		- 1.5	V	
V _{OH}	'LS595 Q	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX	I _{OH} = - 1 mA		2.4	3.2		V	
	I _{OH} = - 2.6 mA				2.4	3.1			
	Q _H '		I _{OH} = - 1 mA		2.4	3.2	2.4		3.2
I _{OH}	'LS596 Q	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX, V _{OH} = 5.5 V			0.1		0.1	mA	
V _{OL}	Q	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX	I _{OL} = 12 mA		0.25	0.4	0.25	0.4	V
	I _{OL} = 24 mA				0.35	0.5			
	I _{OL} = 8 mA		0.25	0.4	0.25	0.4			
	Q _H '		I _{OL} = 16 mA				0.35	0.5	
I _{OZH}	'LS595 Q	V _{CC} = MAX, V _{IH} = 2 V, V _{IL} = MAX, V _{OH} = 2.7 V			20		20	μA	
I _{OZL}	'LS595 Q	V _{CC} = MAX, V _{IH} = 2 V, V _{IL} = MAX, V _{OH} = 0.4 V			- 20		- 20	μA	
I _I		V _{CC} = MAX, V _I = 7 V			0.1		0.1	mA	
I _{IH}		V _{CC} = MAX, V _I = 2.7 V			20		20	μA	
I _{IL}	SER	V _{CC} = MAX, V _I = 0.4 V			- 0.4		- 0.4	mA	
	All others				- 0.2		- 0.2		
I _{OS} §	'LS595 Q	V _{CC} = MAX, V _O = 0 V	- 30		- 130	- 30		- 130	mA
	Q _H '		- 20		- 100	- 20		- 100	
I _{CCH}	'LS595	V _{CC} = MAX, All possible inputs grounded, All outputs open	33		50	33		50	mA
	'LS596		30		45	30		45	
I _{CCL}	'LS595		42		65	42		65	mA
	'LS596		36		55	36		55	
I _{CCZ}	'LS595		44		65	44		65	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

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SN54LS595, SN54LS596, SN74LS595, SN74LS596 **8-BIT SHIFT REGISTERS WITH OUTPUT LATCHES**

switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS595			'LS596			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	SRCK $\uparrow$	Q_H'	$R_L = 1\text{ k}\Omega$, $C_L = 30\text{ pF}$		12	18		14	21	ns
t_{PHL}					17	25		20	30	ns
t_{PLH}	RCK $\uparrow$	Q_A thru Q_H	$R_L = 667\ \Omega$, $C_L = 45\text{ pF}$		12	18		28	42	ns
t_{PHL}					24	35		24	35	ns
t_{PZH}	$\overline{G} \downarrow$	Q_A thru Q_H			20	30				ns
t_{PZL}					25	38				ns
t_{PHZ}	$\overline{G} \uparrow$	Q_A thru Q_H	$R_L = 667\ \Omega$, $C_L = 5\text{ pF}$		20	30				ns
t_{PLZ}					25	38				ns
t_{PLH}	$\overline{G} \uparrow$	Q_A thru Q_H	$R_L = 667\ \Omega$, $C_L = 45\text{ pF}$					40	60	ns
t_{PHL}	$\overline{G} \downarrow$	Q_A thru Q_H						25	38	ns
t_{PHL}	SRCLR $\downarrow$	Q_H'	$R_L = 1\text{ k}\Omega$, $C_L = 30\text{ pF}$		24	35		24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86717012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86717012A SNJ54LS 595FK	Samples
5962-8671701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701EA SNJ54LS595J	Samples
5962-8671701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701EA SNJ54LS595J	Samples
5962-8671701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W	Samples
5962-8671701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W	Samples
SN54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS595J	Samples
SN54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS595J	Samples
SN74LS595D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS595DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595	Samples
SN74LS595N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS595N	Samples
SN74LS595N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS595N	Samples
SN74LS595N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS595N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS595NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS595N	Samples
SN74LS595NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS595N	Samples
SN74LS596D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74LS596D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74LS596N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS596N	Samples
SN74LS596N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS596N	Samples
SN74LS596NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS596N	Samples
SN74LS596NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS596N	Samples
SNJ54LS595FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86717012A SNJ54LS 595FK	Samples
SNJ54LS595FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86717012A SNJ54LS 595FK	Samples
SNJ54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701EA SNJ54LS595J	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701EA SNJ54LS595J	Samples
SNJ54LS595W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W	Samples
SNJ54LS595W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54LS595, SN74LS595 :

- Catalog: [SN74LS595](#)
- Military: [SN54LS595](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS595DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS595DR	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP2-F16

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



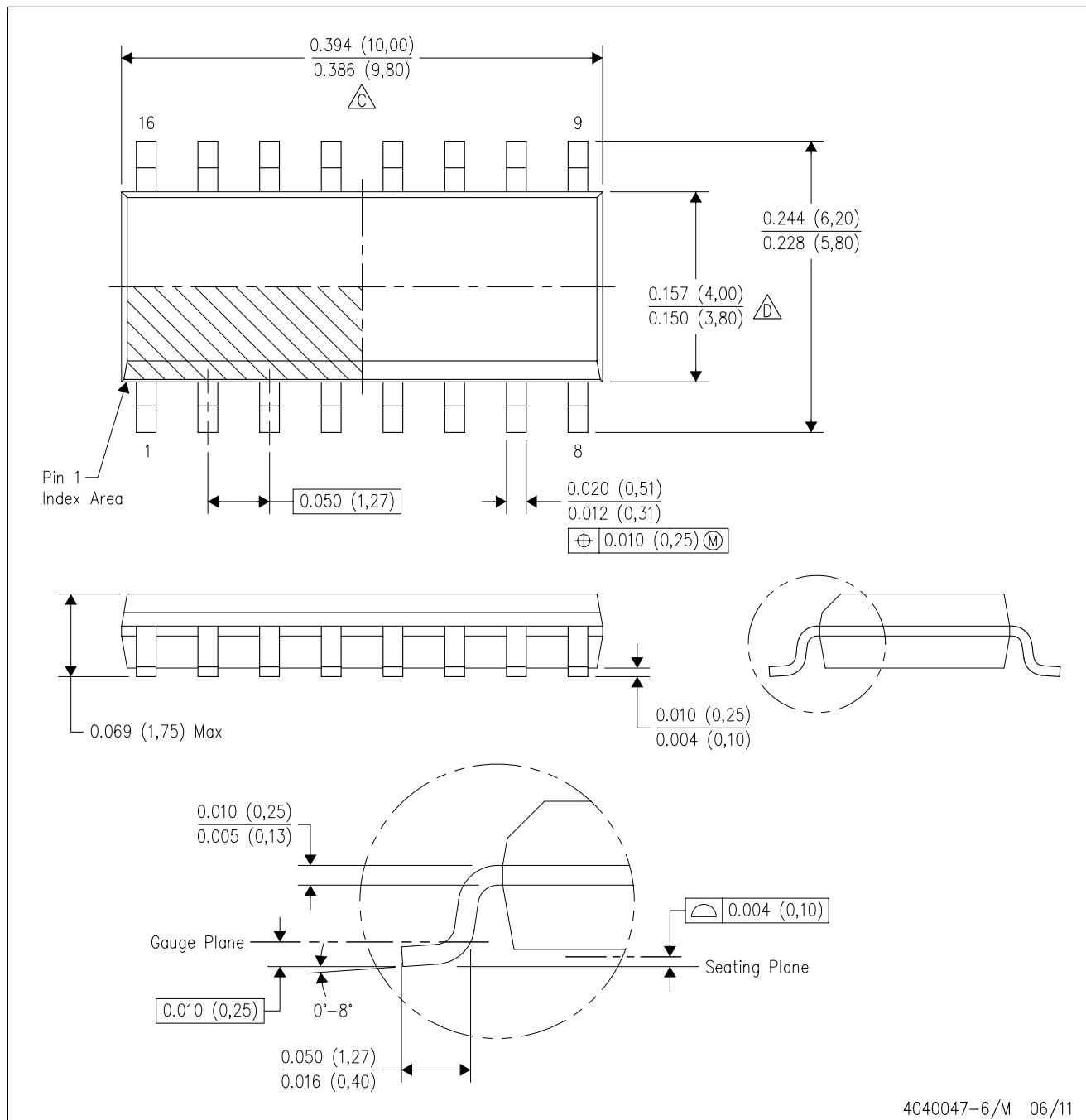
14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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